



晶圓研磨砂輪 Wafer Grinding Wheels

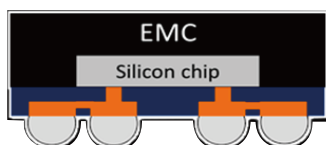


Wafer grinding wheels are used in the in-feed grinding process of semiconductor wafers thinning for TSV package (WLP, PLP) and Si, SiC wafers.

Feature

- Wafer grinding wheels are made of diamond abrasives and customized vitrified bond in a unique porous microstructure.
- Wafer grinding wheels perform a stable high removal rate, longer lifetime and lower/consistent grinding resistance during processing.

Application



Material	Wheel
Pure Compound (EMC) Compound + Silicon chip Compound + Copper via	Z1 #800~#2000 Z2 #3000~#5000
Si, SiC wafer	Z1 #325~#1500 Z2 #2000~#8000

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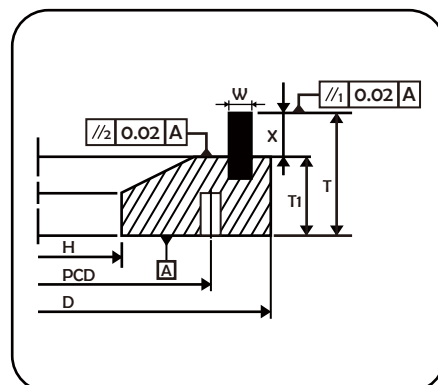
TEL 886-2-26791931 FAX 886-2-26703031 <http://www.kinik.com.tw>

● Wheel Type

Bond	Application		Grit Size(Mesh)										
			#325	#400	#600	#800	#1200	#1500	#2000	#4000	#6000	#8000	#30000
VW	Z1	Coarse	●	●	●	●	●	●	●				
	Z2	Fine							●	●	●	●	●
BH (Vitrified)	Z1	Coarse	●	●	●	●	●	●	●				
	Z2	Fine							●	●			
BW (Resin)	Z1	Coarse	●	●	●								
	Z2	Fine				●	●	●	●	●			

● Wheel Size

Application Equipment		D,Diameter (mm)	T,Thickness (mm)	H,Hole (mm)	W,Width (mm)	X,Height (mm)
Type-D	8"	208.7	22.5	158.0	2.5~5	5~10
	12"	312.0	30.0	237.0		
Type-T	10"	254.0	30.0	190.0		
	12"	304.0	30.0	240.0		
Type-O	10"	254.0	33.0	155.0		
	12"	304.0	35.0	190.0		
Type-S	10"	255.0	33.0	155.0		



● Performance Data: Compound+Copper Via

Wafer		KINIK	Competitor
		Compound+Copper via	
Wheel Spec.	Z1	#600VW	#600
	Z2	#4000VW	#4000
Current(A)		9~10	8~9
Tip wear(μ m)		8~9	9~10
Roughness,Ra(μ m)		0.025	0.026

● Performance Data: Silicon wafer

Wafer		8"Si wafer	6" SiC wafer	
Wheel Spec : Z2	Bond	VW	VW	
	Mesh	#6000~8000	#2000	#8000
Current(A)		7~9	~	15
Tip wear(μ m)		0.5~2	0.4	~
Roughness,Ra(μ m)		0.011	0.025	0.005